

ABSTRACT OF THE DISCLOSURE

A bonding method is provided in which an electronic component is connected via bumps to a substrate and the electronic component is packaged on the substrate. A surface of the substrate that packages the electronic component, a surface of the electronic component that is connected to the substrate, and a surface of the bumps undergo plasma processing. Subsequently, the bumps are heated to a temperature lower than a melting point of the bumps, and the substrate and the electronic component are compression bonded via the bumps.